STRIVE FOR EXCELLENCE

Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field	

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-02-26
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by
MDF Champion
Date: 2025.02.26
15:30:45 CET

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H563VGT6	261L*484XXXX	A	9991	2025-02-26
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	684	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	14x14	100	Gull wing	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	**Description**	
,		

QueryList : REACH-21st January 2025				**Response**
QUERY				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**261L*484XXXX**		684.4502		6000000.0	1000000.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	10.134	mg	supplier	die	Silicon (Si)	7440-21-3		9.706	mg	957701	14180.45
				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	2014	29.82
				supplier	metallization	Copper (Cu)	7440-50-8		0.182	mg	17912	265.22
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	72	1.07
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.059	mg	5827	86.28
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	216	3.20
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	144	2.13
				supplier	Passivation	Silicon Nitride	12033-89-5		0.046	mg	4532	67.10
				supplier	Passivation	Silicon Oxide	7631-86-9		0.117	mg	11582	171.49
Leadframe (C7025 + Ag)	Copper & its alloys	190.000	mg	supplier	Leadframe	Copper (Cu)	7440-50-8		174.610	mg	919000	255109.87
				supplier	Leadframe	Nickel (Ni)	7440-02-0		5.890	mg	31000	8605.45
				supplier	Leadframe	Silicon (Si)	7440-21-3		2.280	mg	12000	3331.14
				supplier	Leadframe	Magnesium (Mg)	7439-95-4		0.570	mg	3000	832.79
				supplier	Leadframe	Siliver (Ag)	7440-22-4		6.650	mg	35000	9715.83
Glue Epoxy (EN-4900G)	Precious metals	1.958	mg	supplier	Glue or tape	Silver (Ag)	7440-22-4		1.525	mg	779000	2228.13
				supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.049	mg	25000	71.51
				supplier	Glue or tape	Bisphenol A Diacrylate	Proprietary		0.119	mg	61000	174.47
				supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.108	mg	55000	157.31
				supplier	Glue or tape	Butadiene copolymer	Proprietary		0.020	mg	10000	28.60
				supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.108	mg	55000	157.31
				supplier	Glue or tape	Peroxy Ketals	Proprietary		0.010	mg	5000	14.30
				supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.010	mg	5000	14.30
				supplier	Glue or tape	Methacrylate multialkoxysubstitutedalkyl ester	Proprietary		0.010	mg	5000	14.30
Bonding wire (Cu)	Precious metals	1.513	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		1.461	mg	965500	2134.27
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.047	mg	31000	68.53
				supplier	Bonding wire	Silver (Ag)	7440-22-4		0.005	mg	3500	7.74
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	459.945	mg	supplier	Molding Compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-diy	85954-11-6		18.398	mg	40000	26879.68
				supplier	Molding Compound	Epoxy resin	Proprietary		9.199	mg	20000	13439.84
				supplier	Molding Compound	Phenol Resin	Proprietary		34.496	mg	75000	50399.39
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		326.331	mg	709500	476778.27
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		68.992	mg	150000	100798.79
				supplier	Molding Compound	Carbon black	1333-86-4		2.530	mg	5500	3695.96
External Plating (Sn)	M-011 Other inorganic materials	20.900	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		20.898	mg	999900	30532.40
				supplier	Matte Sn	Impurities	Proprietary		0.002	mg	100	3.05